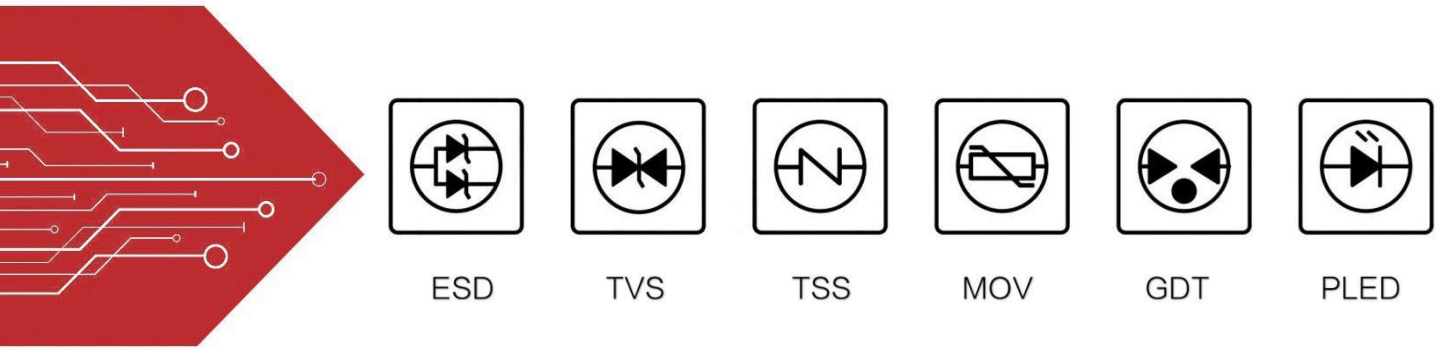
MSKSEMI
SEMICONDUCTOR



Product data sheet

Features

- 400W peak pulse power (8/20μs)
- Ultra low leakage: nA level
- Operating voltage: 7V or 12V
- Low clamping voltage
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
    - Air discharge: ±30kV
    - Contact discharge: ±30kV
  - IEC61000-4-4 (EFT) 40A (5/50ns)
  - IEC61000-4-5 (Lightning) 17A (8/20μs)
- RoHS Compliant

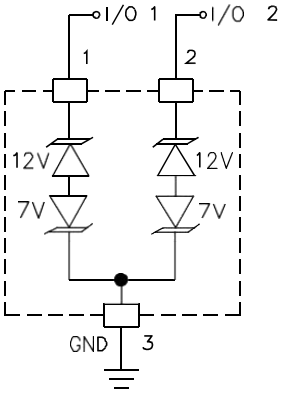
Mechanical Characteristics

- Package: SOT-23
- Lead Finish: Matte Tin
- Case Material: “Green” Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram Below

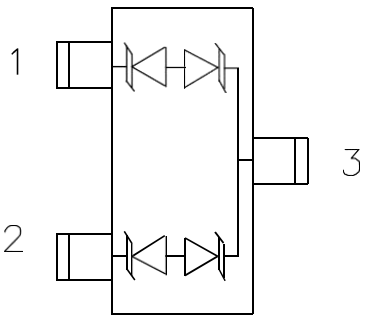
Applications

- Wireless System
- Networks
- Portable Instrumentation
- RS485 Ports

Circuit Diagram



Pin Configuration



Absolute Maximum Ratings (Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20μs)	Ppk	400	W
Peak Pulse Current (8/20μs)	Ipp	12	A
ESD per IEC 61000−4−2 (Air) ESD per IEC 61000−4−2 (Contact)	V_{ESD}	±30 ±30	kV
Operating Temperature Range	T_J	−55 to +125	°C
Storage Temperature Range	Tstg	−55 to +150	°C

Electrical Characteristics (TA=25°C unless otherwise specified)

		Pin 1 to 3 and 2 to 3 (12V TVS)			Pin 3 to 1 and 3 to 2 (7V TVS)				
Parameter	**Symbol**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**	**Test Condition**
Reverse Working Voltage	V_{RWM}			12			7	V	
Breakdown Voltage	V_{BR}	13.3			7.5			V	I_T = 1mA
Reverse Leakage Current	I_R			0.05			2.0	uA	$V_R = V_{RWM}$
Clamping Voltage	V_C			20			10	V	I_{PP} = 5A (8 x 20μs pulse)
Clamping Voltage	V_C			26			12	V	I_{PP} = 12A (8 x 20μs pulse)
Junction Capacitance	C_J			75			75	pF	VR = 0V, f = 1MHz
Junction Capacitance	C_J		45			45		pF	$V_R = V_{RWM}$, f = 1MHz

Electrical Parameter

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
I_T	Test Current
V_{BR}	Breakdown Voltage @ I_T

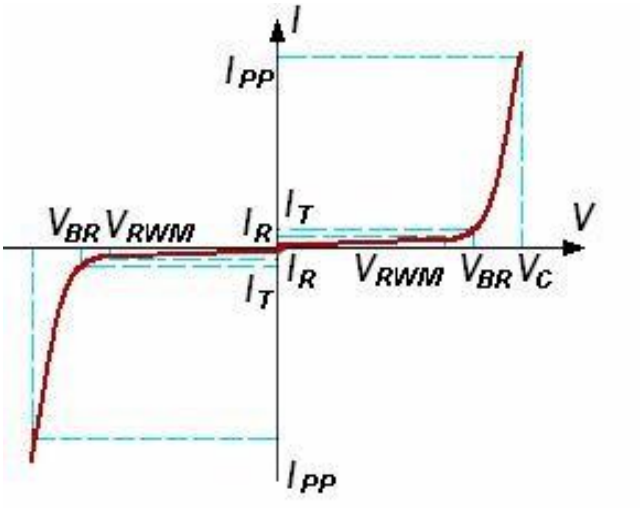


FIG1: Pulse Waveform

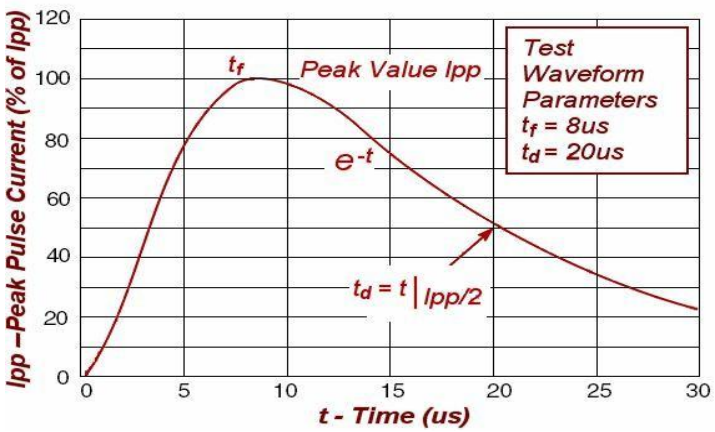
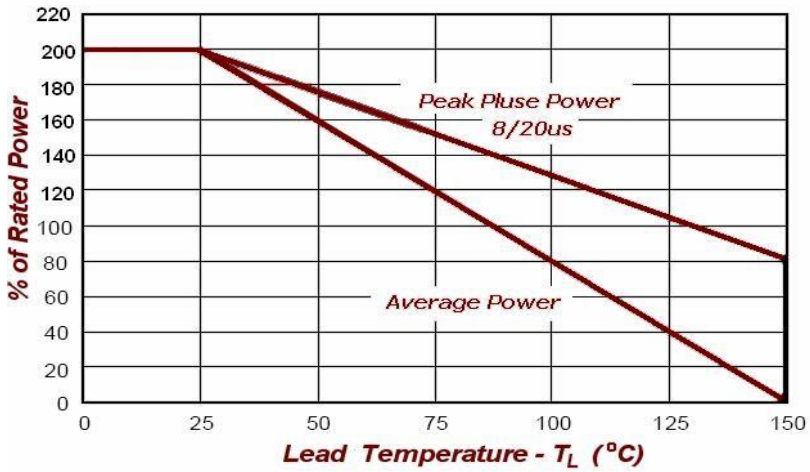
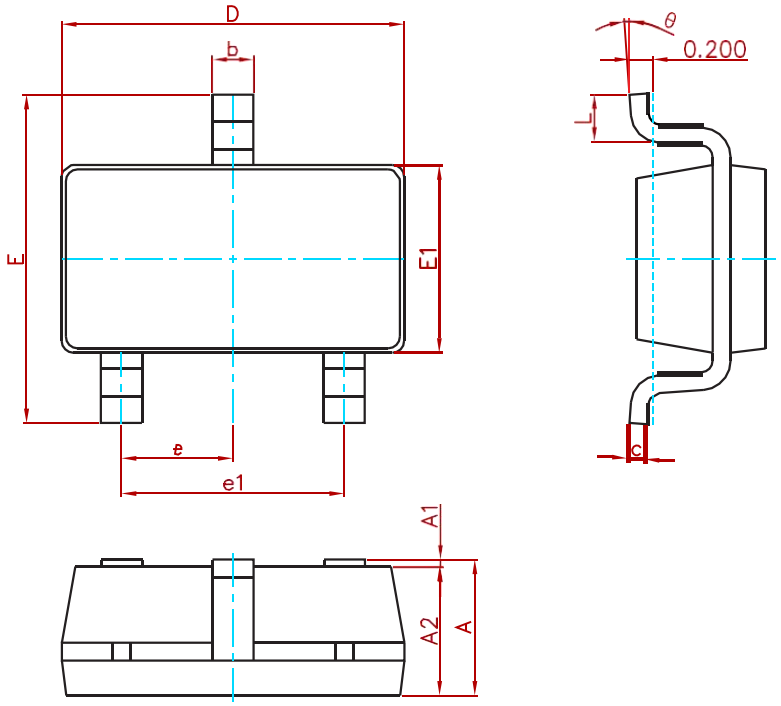


FIG2:Power Derating

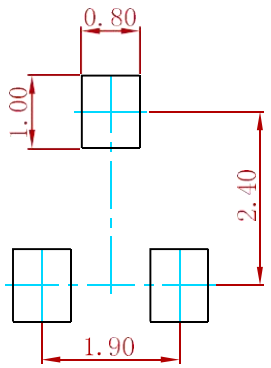


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
0	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
PSM712-MS	SOT-23	3000

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